

ANTREX Electronics

Electronic Components Sourcing Information

Product Reference Information

Part Number:	DMN10H170SFGQ-7
Manufacturer:	Diodes Incorporated
Package:	Please confirm with sales
Availability:	Please confirm with sales

Product Page:

<https://antrexco.com/product/details/diodes-incorporated/dmn10h170sfgq-7.html>

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New & Original Components

Supplier verification and packaging condition review

CoC / RoHS / REACH documents available on request

Secure sourcing support for OEM / EMS projects

Note:

This PDF includes an ANTREX product reference cover page.

The original manufacturer datasheet follows from the next page.

Product Summary

BV_{DSS}	$R_{DS(ON)}$ max	I_D max $T_A = +25^\circ\text{C}$
100V	122m Ω @ $V_{GS} = 10\text{V}$	2.9A
	133m Ω @ $V_{GS} = 4.5\text{V}$	2.7A

Description and Applications

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

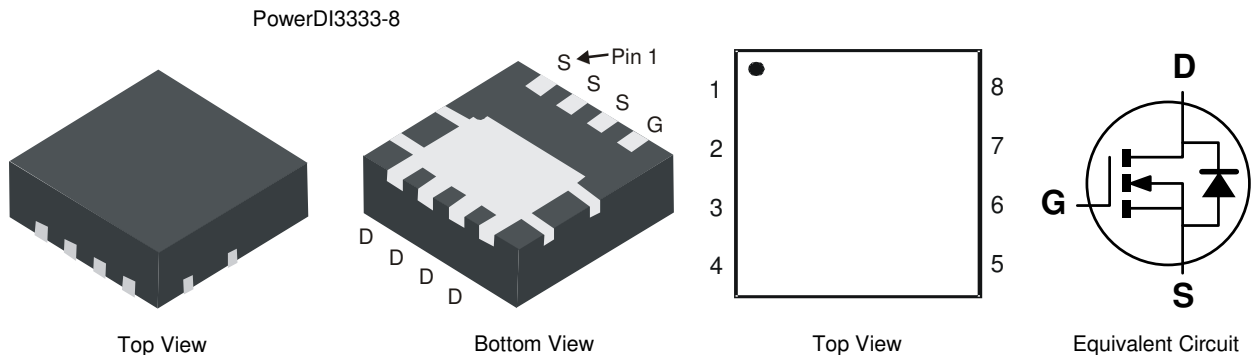
- Motor Control
- Power Management Functions
- DC-DC Converters

Features

- 100% Unclamped Inductive Switching, Test in Production – Ensures more reliable and robust end application
- Low $R_{DS(ON)}$ – Ensures on state losses are minimized
- Small form factor thermally efficient package enables higher density end products
- Occupies just 33% of the board area occupied by SO-8 enabling smaller end product
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

Mechanical Data

- Case: PowerDI[®]3333-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208@3
- Weight: 0.03 grams (Approximate)

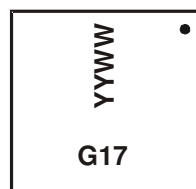


Ordering Information (Note 5)

Part Number	Case	Packaging
DMN10H170SFGQ-7	PowerDI3333-8	2000/Tape & Reel
DMN10H170SFGQ-13	PowerDI3333-8	3000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to <https://www.diodes.com/quality/>.
 5. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



G17 = Product Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 19 for 2019)
WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	100	V
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note 7) V _{GS} = 10V	Steady State	T _A = +25°C	I _D	2.9	A
		T _A = +70°C		2.4	
		T _C = +25°C		8.5	
	t < 10s	T _A = +25°C	I _D	3.7	A
				3.0	A
Maximum Continuous Body Diode Forward Current (Note 7)			I _S	3.0	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	16	A
Avalanche Current (Note 8)			I _{AS}	5.3	A
Avalanche Energy (Note 8)			E _{AS}	20	mJ

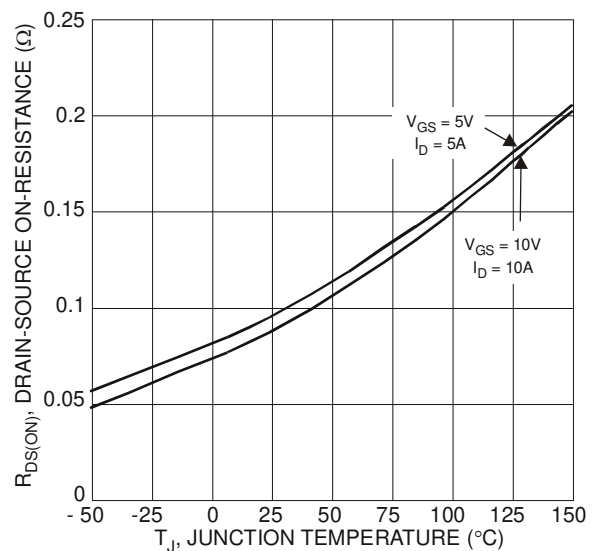
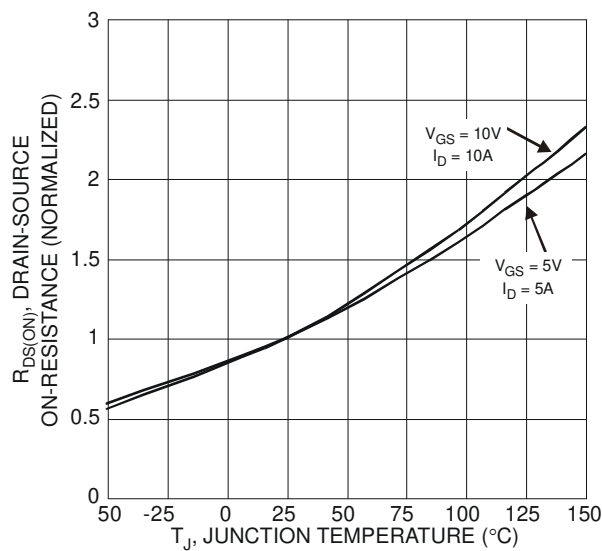
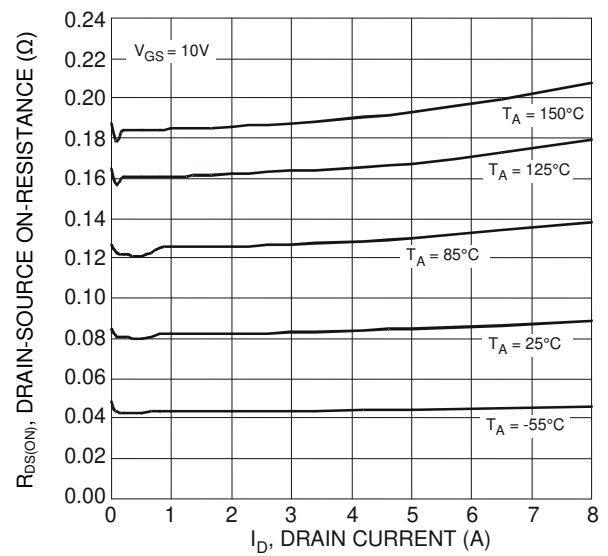
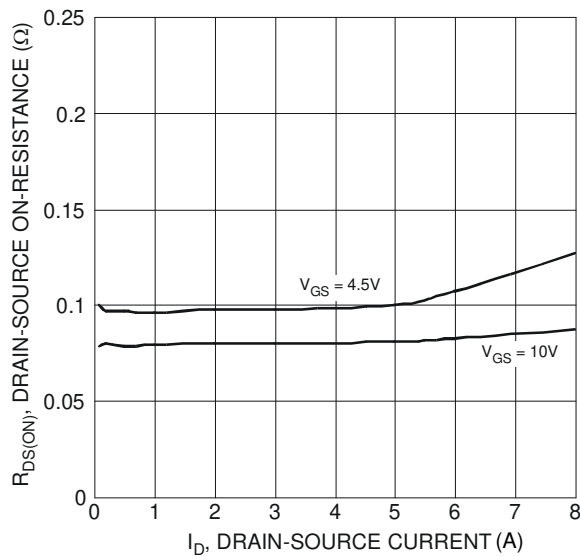
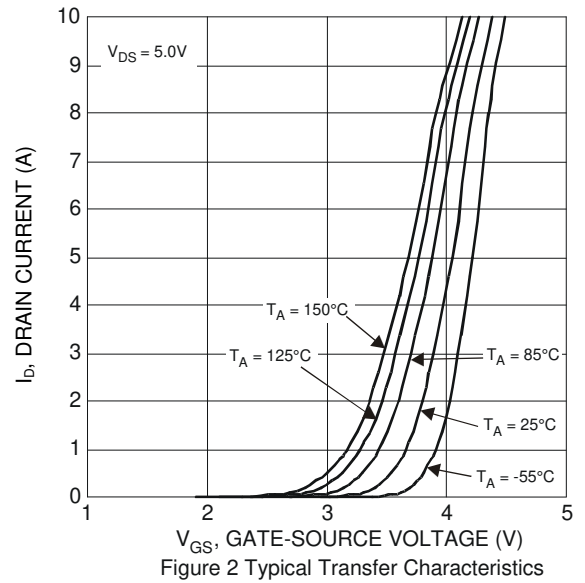
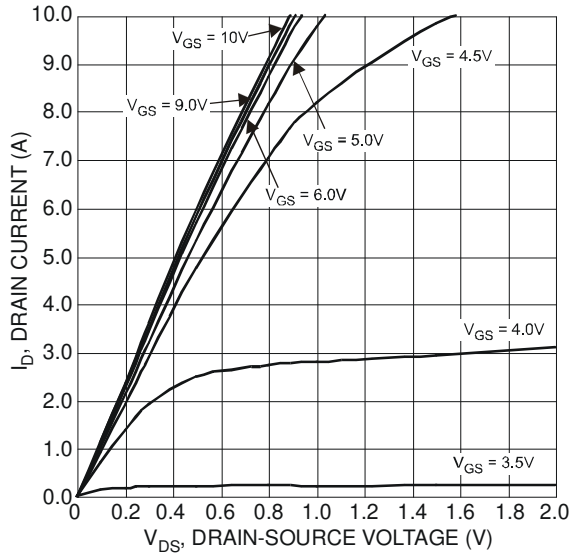
Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)	T _A = +25°C	P _D	0.94	W
	T _A = +70°C		0.6	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R _{θJA}	137	°C/W
	t < 10s		82	
Total Power Dissipation (Note 7)	T _A = +25°C	P _D	2.0	W
	T _A = +70°C		1.3	
Thermal Resistance, Junction to Ambient (Note 7)	Steady State	R _{θJA}	60	°C/W
	t < 10s		36	
Thermal Resistance, Junction to Case (Note 7)		R _{θJC}	7.0	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BV _{DSS}	100	—	—	V	V _{GS} = 0V, I _D = 250µA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1.0	µA	V _{DS} = 100V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	V _{GS(TH)}	1.0	—	3.0	V	V _{DS} = V _{GS} , I _D = 250µA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	99	122	mΩ	V _{GS} = 10V, I _D = 3.3A
		—	104	133		V _{GS} = 4.5V, I _D = 3.0A
Forward Transfer Admittance	Y _{fs}	—	4.4	—	S	V _{DS} = 10V, I _D = 3.3A
Diode Forward Voltage	V _{SD}	—	0.7	1.0	V	V _{GS} = 0V, I _S = 3.3A
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	C _{iss}	—	870.7	—	pF	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	—	40.8	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	24.6	—	pF	
Gate Resistance	R _g	—	1.1	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1.0MHz
Total Gate Charge (V _{GS} = 4.5V)	Q _g	—	7.0	—	nC	V _{DS} = 50V, I _D = 3.3A
Total Gate Charge (V _{GS} = 10V)	Q _g	—	14.9	—	nC	
Gate-Source Charge	Q _{gs}	—	3.3	—	nC	
Gate-Drain Charge	Q _{gd}	—	3.0	—	nC	
Turn-On Delay Time	t _{D(ON)}	—	4.4	—	ns	V _{DD} = 50V, V _{GEN} = 10V, R _{GEN} = 6.0Ω, I _D = 3.3A
Turn-On Rise Time	t _R	—	2.3	—	ns	
Turn-Off Delay Time	t _{D(OFF)}	—	13.9	—	ns	
Turn-Off Fall Time	t _F	—	3.4	—	ns	
Reverse Recovery Time	t _{RR}	—	22.4	—	ns	I _S = 3.3A, dI/dt = 100A/µs
Reverse Recovery Charge	Q _{RR}	—	19.7	—	nC	

- Notes:
- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 - Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
 - UIS in production with L = 1.43mH, T_J = +25°C.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to product testing.



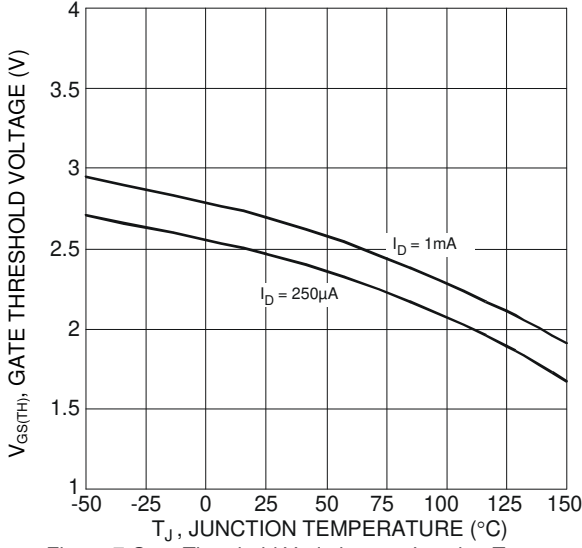


Figure 7 Gate Threshold Variation vs. Junction Temperature

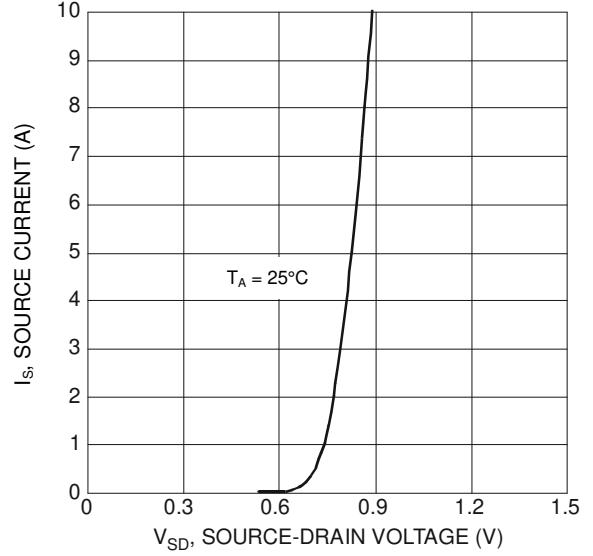


Figure 8 Diode Forward Voltage vs. Current

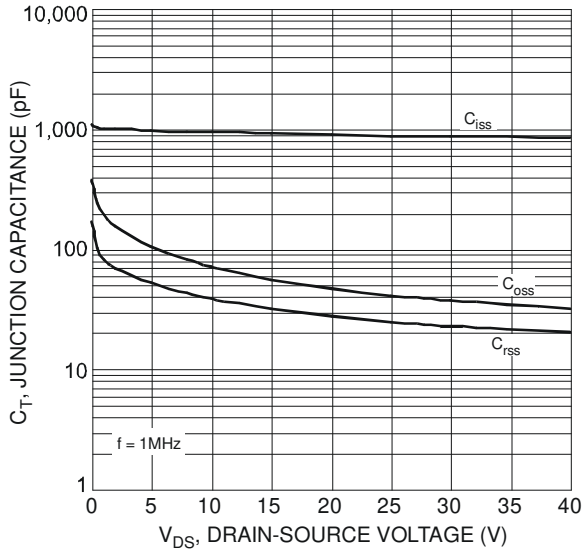


Figure 9 Typical Junction Capacitance

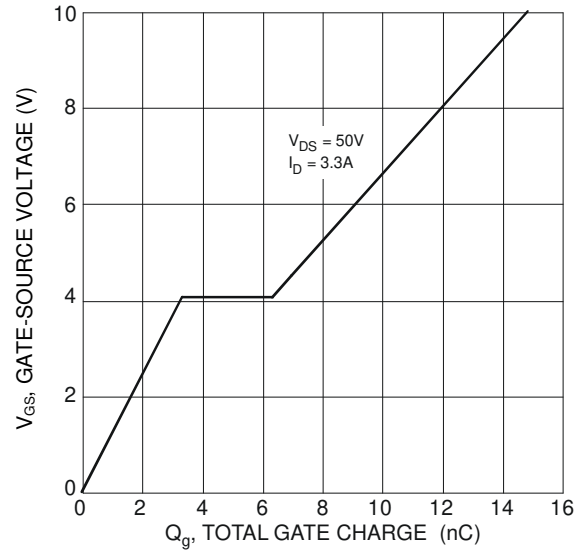


Figure 10 Gate Charge

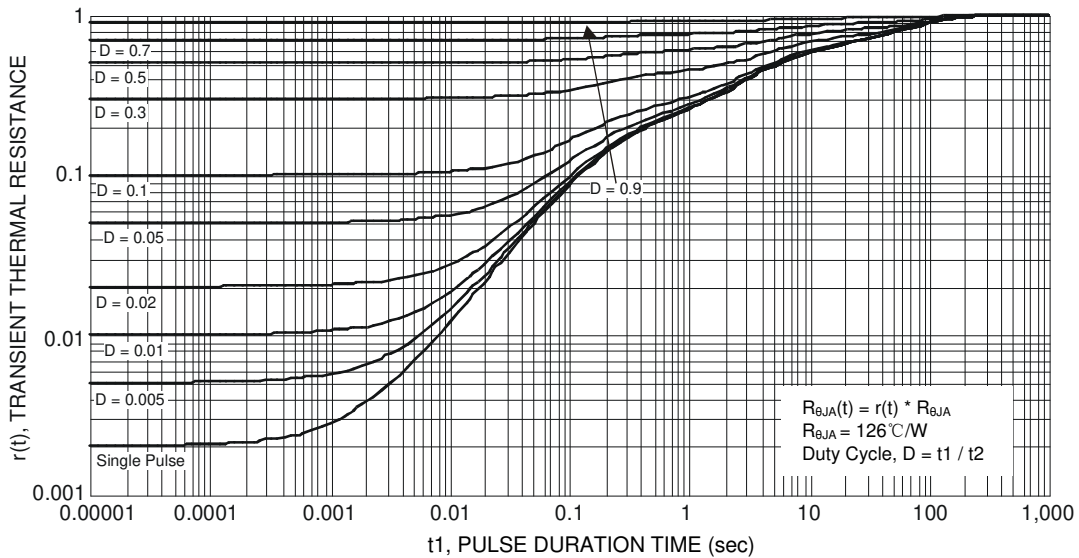
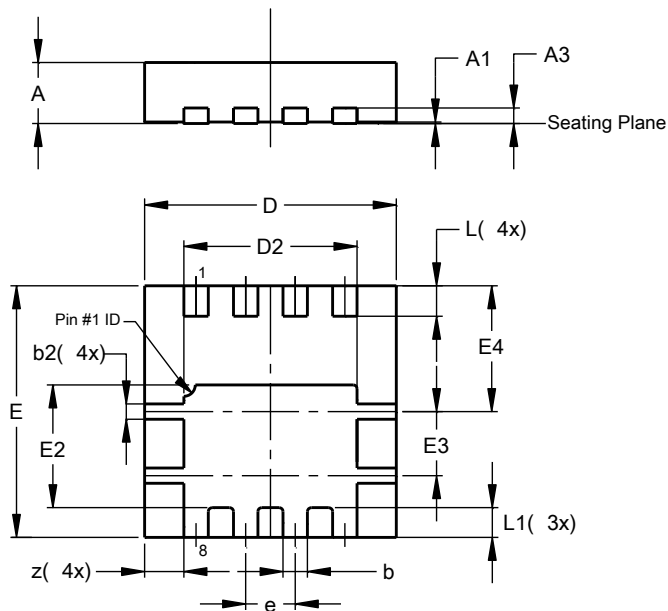


Figure 11 Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI3333-8

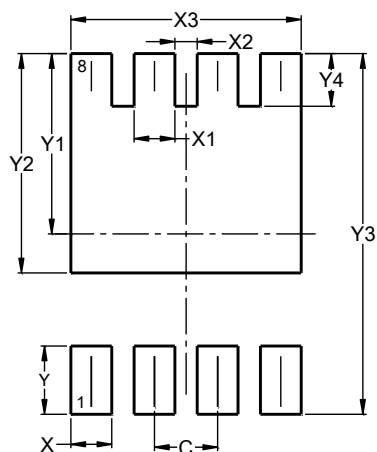


PowerDI3333-8			
Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0.00	0.05	0.02
A3	—	—	0.203
b	0.27	0.37	0.32
b2	0.15	0.25	0.20
D	3.25	3.35	3.30
D2	2.22	2.32	2.27
E	3.25	3.35	3.30
E2	1.56	1.66	1.61
E3	0.79	0.89	0.84
E4	1.60	1.70	1.65
e	—	—	0.65
L	0.35	0.45	0.40
L1	—	—	0.39
z	—	—	0.515
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI3333-8



Dimensions	Value (in mm)
C	0.650
X	0.420
X1	0.420
X2	0.230
X3	2.370
Y	0.700
Y1	1.850
Y2	2.250
Y3	3.700
Y4	0.540

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